



Overview and Capabilities

Chip Supply has been working in the semiconductor industry for over 25 years. Beginning as one of the first distributors of bare die products to the military market, Chip Supply has since evolved into a first class value add processor and supplier to several markets. Chip Supply's offerings are centered on the availability of bare die and wafers. We have mastered the ability to saw, sort and inspect wafers, where the inspection may be specified by the customer. Electrical testing, wafer probe and environmental screening are test services that are also provided, typically in accordance with a customer's SCD or the manufacturer's datasheet. Coupled with our bare die expertise is our ability to provide packaging solutions. Chip Supply's packaging capabilities feature Chip Scale Packaging (CSP) and a QML certified assembly line per MIL-PRF-38535. Chip Supply also has the ability to offer customized interconnect solutions for those customers in need of specialized packaging. Whether your interconnect demand requires an optimized die solution, a fully customized laminate solution or a hard to find military package, Chip Supply has the in house semiconductor supply, design, manufacturing, test and environmental screening expertise to source your needs.

Capabilities

- **Wafer Saw, Sort, and Inspect**
 - Ship in waffle packs, Gel Pak®, tape on reel, wafer-on-tape
- **Electrical Test / Environmental Screening**
 - Lot acceptance testing
 - Wafer probe (-45C to +140C)
- **Wafer Thinning**
- **Wafer Bumping**
 - Solder or gold bumps
 - Redistribution of bond pads (RDL)
- **Die Banking**
 - Storage and disbursement of last time buys
 - Kitting, JIT shipments
- **Known Good Die (KGD)**
 - Tested at speed, at temperature
 - Burned in, if necessary
 - Equivalent quality and reliability to packaged device
 - Patented SofTAB™ process and others
- **Tape Automated Bond or Tape Carrier Packaging (TCP)**
 - Gang or single-point bonding
 - Package design in house
 - Test and burn in
- **Hermetic assembly**
 - QML certified assembly line – MIL-PRF-38535
 - Flat pack, PGA, DIP, can, LCC
 - Where military package flows are unavailable from the manufacturer
- **Chip Scale Packaging**
 - Near-chip size package
 - BGA (.5mm – 1.0mm+ ball pitch) interconnect
 - QFN (plastic Quad Flatpack No leads, sometimes called MLF®, Micro Lead Frame)
 - Package design in house
 - Cost effective combined test and burn-in offered
- **Multi-Chip Modules / SIP**
 - Custom design, fabrication and test



Chip Supply Sales Offices

Headquarters—Orlando, FL
P: 407.298.7100

Northeast Office—Philadelphia, PA
Christine Unger—215.943.5103

Central US Sales Office—Austin, TX
Kevin Kendrick—512.261.3335

Western US Sales Office—San Jose, CA
Mark Hartung—408.517.0640

European & UK Sales Office
John Kay—44.161.633.6627



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